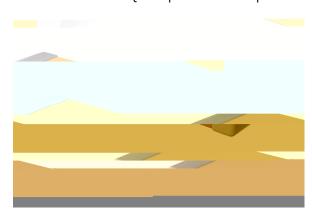


classification are temperature compensating and are

Capacitance change is limited to ±30ppm/°C from -55°C

and fnd conventional use as snubbers or flters in

Electronics Council's AEC-Q200 qualification requirements.



	Specification/				
		signifcant			

¹ Additional capacitance tolerance offerings may be available. Contact KEMET for details.

 $^{^{2}}$ Additional termination finish options may be available. Contact KEMET for details.



¹ Reeling tape options (Paper or Plastic) are dependent on capacitor case size (L" x W") and thickness dimension. See "Chip Thickness/Tape & Reel Packaging Quantities" and "Tape & Reel Packaging Information".

Bene f ts

- · AEC-Q200 automotive qualifed
- Operating temperature range of -55°C to +125°C

Capacitance offerings ranging from 1pF to 0.150μF

² The 2 mm pitch option allows for double the packaging quantity of capacitors on a given reel size. This option is limited to EIA 0603 (1608 metric) case size devices. For more information regarding 2 mm pitch option see "Tape & Reel Packaging Information".

³ All Automotive packaging C-Specs listed exclude the option to laser mark components. Please contact KEMET if you require a laser marked option. For more information see "Capacitor Marking".

³ For additional Information regarding "AUTO" C-Spec options, see "Automotive C-Spec Information."



Details regarding test methods and conditions are referenced in document AEC-Q200, Stress Test Qualification for Passive Components. These products are supported by a Product Change Notification (PCN) and Production Part Approval Process

component without the requirement to submit a customer Source Controlled Drawing (SCD) or specification for review by a

Product Change Notification (PCN)

The KEMET Product Change Notification system is used to communicate primarily the following types of changes:

• Product/process changes that affect product form, ft, function, and/or reliability

Customer Notifica	Customer Notification due to:						

KEMET assigned C-Specs require the submittal of a customer SCD or customer specification for review. For additional information contact KEMET.

The purpose of the Production Part Approval Process is:

• To provide the evidence that all customer engineering design record and specification requirements are properly understood and fulfilled by the manufacturing organization.

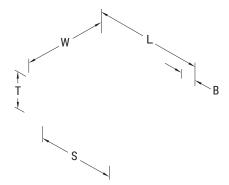
•	•	•	•	•
0		0		

¹ KEMET assigned C-Specs require the submittal of a customer SCD or customer specification for review. For additional information contact KEMET.

• Part number specifc PPAP available

C







Qualif cation/Certif cation

regarding test methods and conditions are referenced in docu	ument AEC–Q200, Stress Test Qualification for Passive
	-55°C to +125°C
	1,000 megohm microfarads or 100 GΩ

Note: When measuring capacitance it is important to ensure the set voltage level is held constant. The HP4284 and Agilent E4980 have a feature known as Automatic Level Control (ALC). The ALC feature should be switched to "ON."

¹ DWV is the voltage a capacitor can withstand (survive) for a short period of time. It exceeds the nominal and continuous working voltage of the capacitor.

 $^{^2}$ Capacitance and dissipation factor (DF) measured under the following conditions:

¹ MHz ± 100 kHz and 1.0 $V_{rms} \pm 0.2$ V if capacitance $\leq 1,000$ pF

¹ kHz ± 50 Hz and 1.0 V $_{rms}$ ± 0.2 V if capacitance > 1,000 pF

 $^{^3}$ To obtain IR limit, divide M Ω - μ F value by the capacitance and compare to G Ω limit. Select the lower of the two limits.



					_	
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-						

^{*}Capacitance range Includes E24 decade values only (i.e., 10, 11, 12, 13, 15, 16, 18, 20, 22, 24, 27, 30, 33, 36, 39, 43, 47, 51, 56, 62, 68, 75, 82, and 91.) KEMET reserves the right to substitute product with an improved temperature characteristic, tighter capacitance tolerance and/or higher voltage capability within the same form factor (configuration and dimensions.)

These products are protected under US Patents 7,172,985 and 7,670,981, other patents pending, and any foreign counterparts.



*Capacitance range Includes E24 decade values only (i.e., 10, 11, 12, 13, 15, 16, 18, 20, 22, 24, 27, 30, 33, 36, 39, 43, 47, 51, 56, 62, 68, 75, 82, and 91.) KEMET reserves the right to substitute product with an improved temperature characteristic, tighter capacitance tolerance and/or higher voltage capability within the same form factor (configuration and dimensions.)

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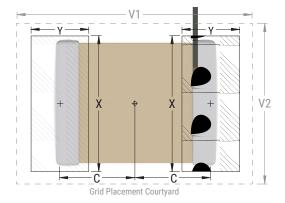
Density Level A:			Density Level B:					Density Level C:					

For low-density product applications. Recommended for wave solder applications and provides a wider process window for reflow solder processes. KEMET only recommends wave soldering of EIA 0603, 0805 and 1206 case sizes.

For products with a moderate level of component density. Provides a robust solder attachment condition for reflow solder processes.

For high component density product applications. Before adapting the minimum land pattern variations the user should perform qualification testing based on the conditions outlined in IPC Standard 7351 (IPC-7351).

Image below based on Density Level B for an EIA 1210 case size.





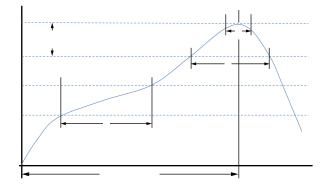
Recommended Soldering Technique:

- Solder wave or solder refow for EIA case sizes 0603, 0805 and 1206
- All other EIA case sizes are limited to solder refow only

Recommended Refow Soldering Profle:

convection, IR or vapor phase refow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET's recommended profle conditions for convection and IR refow refect the profle conditions of the IPC/J-STD-020 standard for moisture sensitivity testing. These devices can safely withstand a maximum of three refow passes at

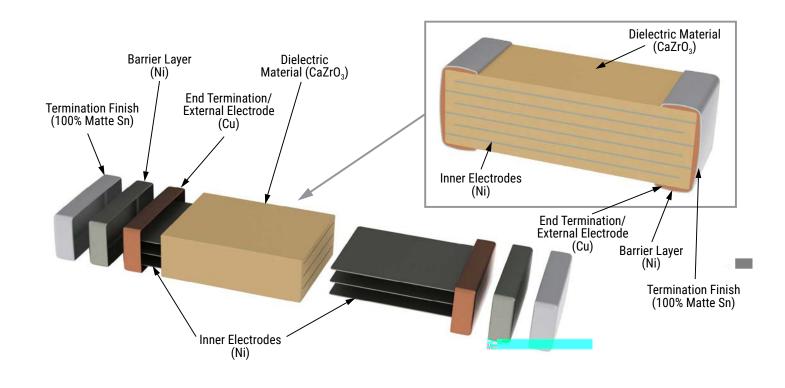
Profle Feature		
T TO TIC T CUITATE		



Note 1: All temperatures refer to the center of the package, measured on the capacitor body surface that is facing up during assembly reflow.

storage humidity not exceed 70% relative humidity. Temperature fuctuations should be minimized to avoid condensation on

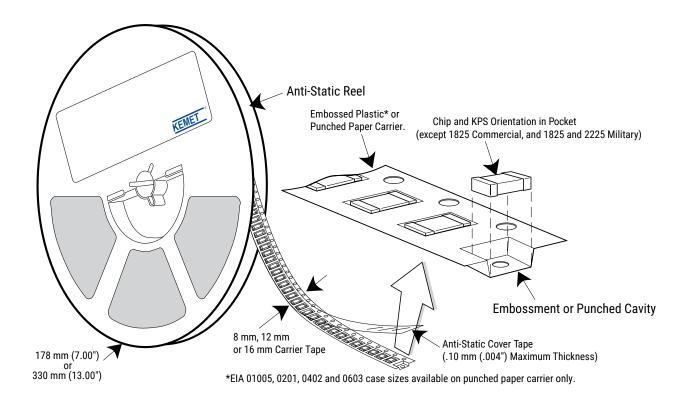




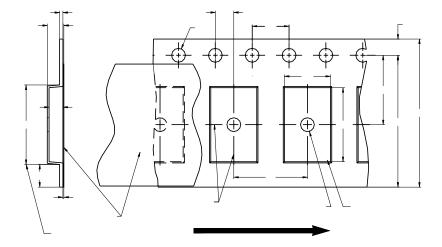
Capacitor Marking (Optional):

Laser marking option is not available on:



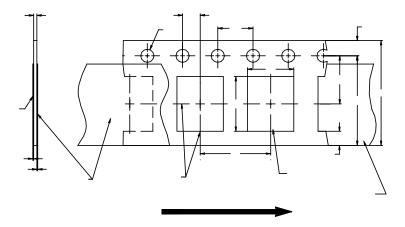






	1.5+0.10/-0.0 (0.059+0.004/-0.0)						





1.5+0.10/-0.0 (0.059+0.004/-0.0)			

- 1. The cavity defined by A_{o} , B_{o} and T shall surround the component with sufficient clearance that:
 - a) the component does not protrude beyond either surface of the carrier tape.
 - b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.
 - c) rotation of the component is limited to 20° maximum (see Figure 3).
 - d) lateral movement of the component is restricted to 0.5 mm maximum (see Figure 4).
 - e) see Addendum in EIA Standard 481 for standards relating to more precise taping requirements.
- 2. The tape with or without components shall pass around R without damage (see Figure 6).

Packaging Information Performance Notes

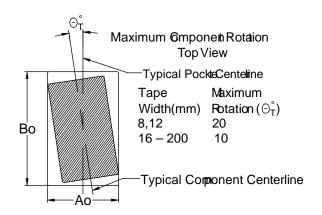
- 'SZIV 8ETI &VIEO *SVGI 1.0 Kg minimum.
- 'SZIV 8ETI 411817XXXSIREKEXLTIIP WXVIRKXL SJ XLI GSZIV XETI JVSQ XLI

Tape Width	Peel Strength	
8 mm	0.1 to 1.0 Newton (10 to 100 gf)	
12 and 16 mm	0.1 to 1.3 Newton (10 to 130 gf)	
24 mm	0.1 to 1.6 Newton (10 to 160 gf)	

The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall 165° to 180° from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity 300±10 mm/minute.

0 E F I P M R K Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket hole 7 X E R H E V H W E R H .

Figure 3 – Maximum Component Rotation



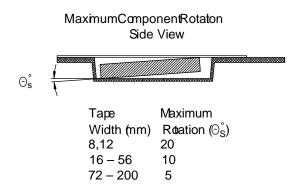
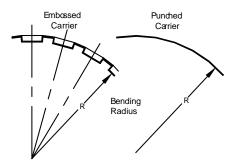
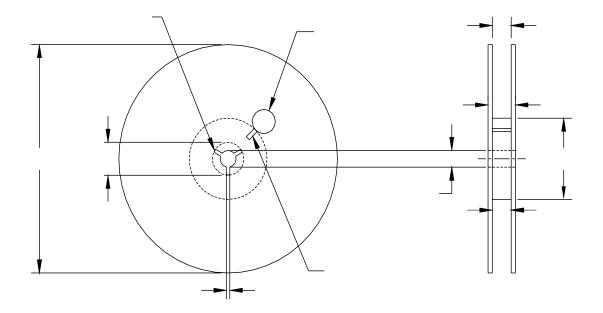


Figure 4 – Maximum Lateral Movement

Figure 5 – Bending Radius

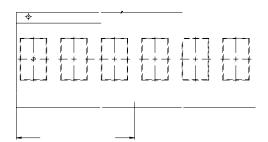






		13.0+0.5/-0.2 (0.521+0.02/-0.008)	
		13.0 + -0.2 (0.521 + -0.008)	
	8.4+1.5/-0.0 (0.331+0.059/-0.0)		
	12.4+2.0/-0.0 (0.488+0.078/-0.0)		
	12.4+2.0/-0.0 (0.488+0.078/-0.0) 16.4+2.0/-0.0 (0.646+0.078/-0.0)		







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(such as installation of protective circuitry or redundancies) in order to ensure that the failure of an electrical component does not result in a risk of personal injury o